



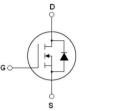
N-Channel Super Junction Power MOSFET II

General Description

The series of devices use advanced super junction technology and design to provide excellent R_{DS(ON)} with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

Features

- New technology for high voltage device
- Low on-resistance and low conduction losses
- Small package
- Ultra Low Gate Charge cause lower driving requirements
- 100% Avalanche Tested
- ROHS compliant





Power factor correction (PFC) Switched mode power supplies(SMPS)

Application

Uninterruptible Power Supply (UPS)

Vds	700	V
Rds(on)typ.	360	mΩ
D	11	A

Schematic diagram

TO-263

Package Marking And Ordering Information

Device	Device Package	Marking
MJ70R360D	TO-263	MJ70R360D

Table 1. Absolute Maximum Ratings (Tc=25℃)

Parameter	Symbol	MJ70R360D	Unit
Drain-Source Voltage (Ves=0V)	Vds	700	V
Gate-Source Voltage (VDs=0V)	Vgs	±30	V
Continuous Drain Current at Tc=25°C	ID (DC)	11	А
Continuous Drain Current at Tc=100°C	Id (dc)	7	А
Pulsed drain current (Note 1)	IDM (pluse)	33	А
Maximum Power Dissipation (Tc=25℃)	Po	121	W
Derate above 25°C	Po	0.97	W/°C
Single pulse avalanche energy (Note 2)	Eas	280	mJ
Avalanche current (Note 1)	lar	5.5	А
Repetitive Avalanche energy, tar limited by $T_{jmax} ^{(Note 1)}$	Ear	0.5	mJ

Parameter	Symbol	MJ70R360D	Unit
Drain Source voltage slope, V⊳s ≤480 V	dv/dt	50	V/ns
Reverse diode dv/dt, V _{DS} ≤480 V,I _{SD} <i<sub>D</i<sub>	dv/dt	15	V/ns
Operating Junction and Storage Temperature Range	Tj,Tstg	-55+150	°C

* limited by maximum junction temperature





Table 2. Thermal Characteristic

Parameter	Symbol	MJ70R360D	Unit
Thermal Resistance, Junction-to-Case (Maximum)	RthJC	1.03	°C/W
Thermal Resistance, Junction-to-Ambient (Maximum)	RthJA	62	°C/W

Table 3. Electrical Characteristics (T_A=25℃ unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Uni
On/off states		I				
Drain-Source Breakdown Voltage	BVDSS	V _{GS} =0V I _D =250µA	700	-	-	V
Zero Gate Voltage Drain Current (Tc=25°C)	IDSS	V _{DS} =700V,V _{GS} =0V	-	0.05	1	μA
Zero Gate Voltage Drain Current (Tc=125°C)	IDSS	V _{DS} =700V,V _{GS} =0V	-	-	100	μA
Gate-Body Leakage Current	lgss	V _{GS} =±30V,V _{DS} =0V	-	-	±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250µA	2.5	3	3.5	V
Drain-Source On-State Resistance	Rds(ON)	Vgs=10V,Id=7A	-	360	400	mΩ
Dynamic Characteristics				1	1	
Forward Transconductance	g FS	VDS=20V,ID=7A	-	8	-	S
Input Capacitance	Cies		-	1030	-	pF
Output Capacitance	Coss	V _{DS} =50V,V _{GS} =0V F=1.0MHz	-	85	-	pF
Reverse Transfer Capacitance	Crss	-	-	4.5	-	pF
Total Gate Charge	Qg		-	23	40	nC
Gate-Source Charge	Qgs	VDS=480V,ID=11A VGS=10V	-	5.7	-	nC
Gate-Drain Charge	Qgd		-	8	-	nC
Intrinsic gate resistance	Rg	f=1 MHz open drain	-	2	-	Ω
Switching times	1			1	1	1
Turn-on Delay Time	td(on)		-	9	-	nS
Turn-on Rise Time	tr	Vdd=380V,Id=5.5A	-	4	-	nS
Turn-Off Delay Time	td(off)	R _G =6.8Ω,V _{GS} =10V	-	40	65	nS
Turn-Off Fall Time	tr		-	4.5	8	nS
Source- Drain Diode Characteristics		11		1	1	1
Source-drain current (Body Diode)	Isd		-	-	11	A
Pulsed Source-drain current (Body Diode)	Isdm	- Tc=25°C -	-	-	33	A
Forward On Voltage	Vsd	Tj=25°C,Isp=11A,Vgs=0V	-	0.9	1.2	V
Reverse Recovery Time	trr		_	245	-	nS
Reverse Recovery Charge	Qrr	Tj=25°C,I⊧=11A di/dt=100A/µs	-	2.4	-	uC
Peak reverse recovery Current	Irrm		_	20	_	A





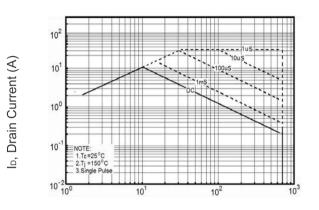
IDR, Reverse Drain Current(A)

Ib, Drain Current (A)

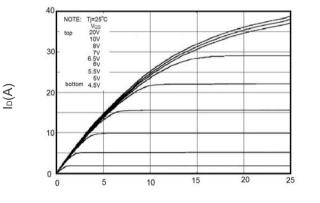
Notes

1.Repetitive Rating: Pulse width limited by maximum junction temperature 2.Tj=25°C,VDD=50V,VG=10V, RG=25 Ω

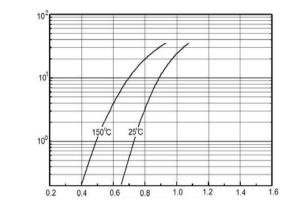
TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)



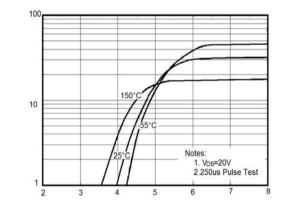
V_{DS}, Drain-Source Voltage (V) Figure 1 Safe operating area



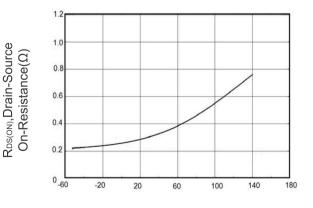
V_{DS}(V) Figure 3 Output characteristics



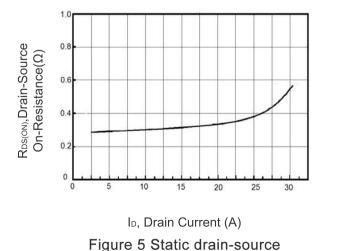
V_{SD},Source-Drain Voltage(V) Figure 2 Source-Drain Diode Forward Voltage



V_{GS}, Gate-Source Voltage (V) Figure 4 Transfer characteristics



TJ, Junction Temperature (°C) Figure 6 RDS(ON) vs Junction Temperature



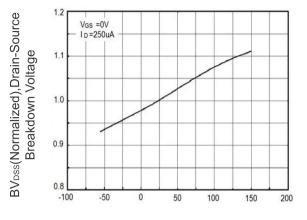
on resistance



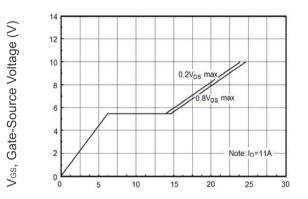


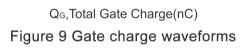
I_D, Drain Current (A)

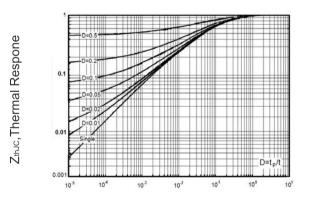
Capacitances(pF)



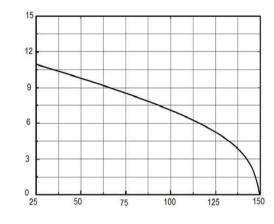
TJ, Junction Temperature (°C) Figure 7 BVDss vs Junction Temperature



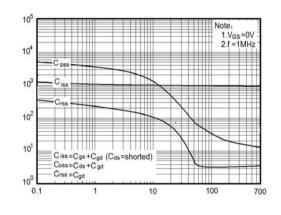




t_₽,Square Wave Pulse(S) Figure 11 Transient Thermal Impedance



Tc, Case Temperature (°C) Figure 8 Maximum ID vs Junction Temperature



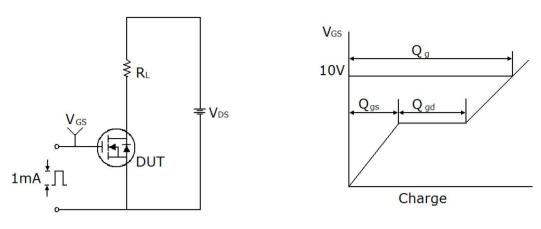
V_{DS}, Drain-Source Voltage (V) Figure 10 Capacitance



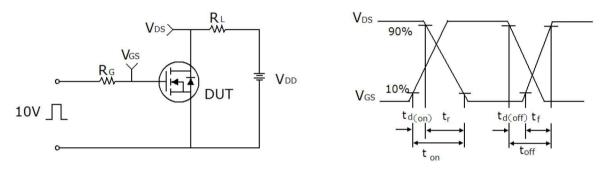




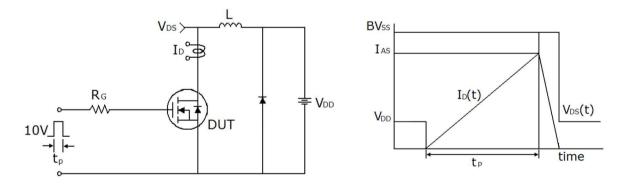
Test circuit



Gate charge test circuit & Waveform



Switch Time Test Circuit

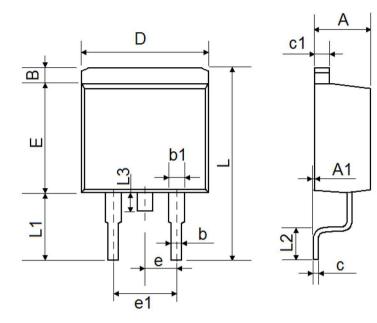


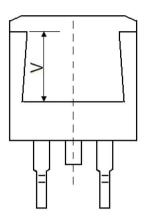
Unclamped Inductive Switching Test Circuit & Waveforms





TO-263-2L Package Information





Symbol	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
A	4.470	4.670	0.176	0.184	
A1	0.000	0.150	0.000	0.006	
В	1.170	1.370	0.046	0.054	
b	0.710	0.910	0.028	0.036	
b1	1.170	1.370	0.046	0.054	
С	0.310	0.530	0.012	0.021	
c1	1.170	1.370	0.046	0.054	
D	10.010	10.310	0.394	0.406	
E	8.500	8.900	0.335	0.350	
e	2.540 TYP.		0.100 TYP.		
e1	4.980	5.180	0.196	0.204	
L	15.050	15.450	0.593	0.608	
L1	5.080	5.480	0.200	0.216	
L2	2.340	2.740	0.092	0.108	
L3	1.300	1.700	0.051	0.067	
V	5.600 REF		0.220 REF		





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